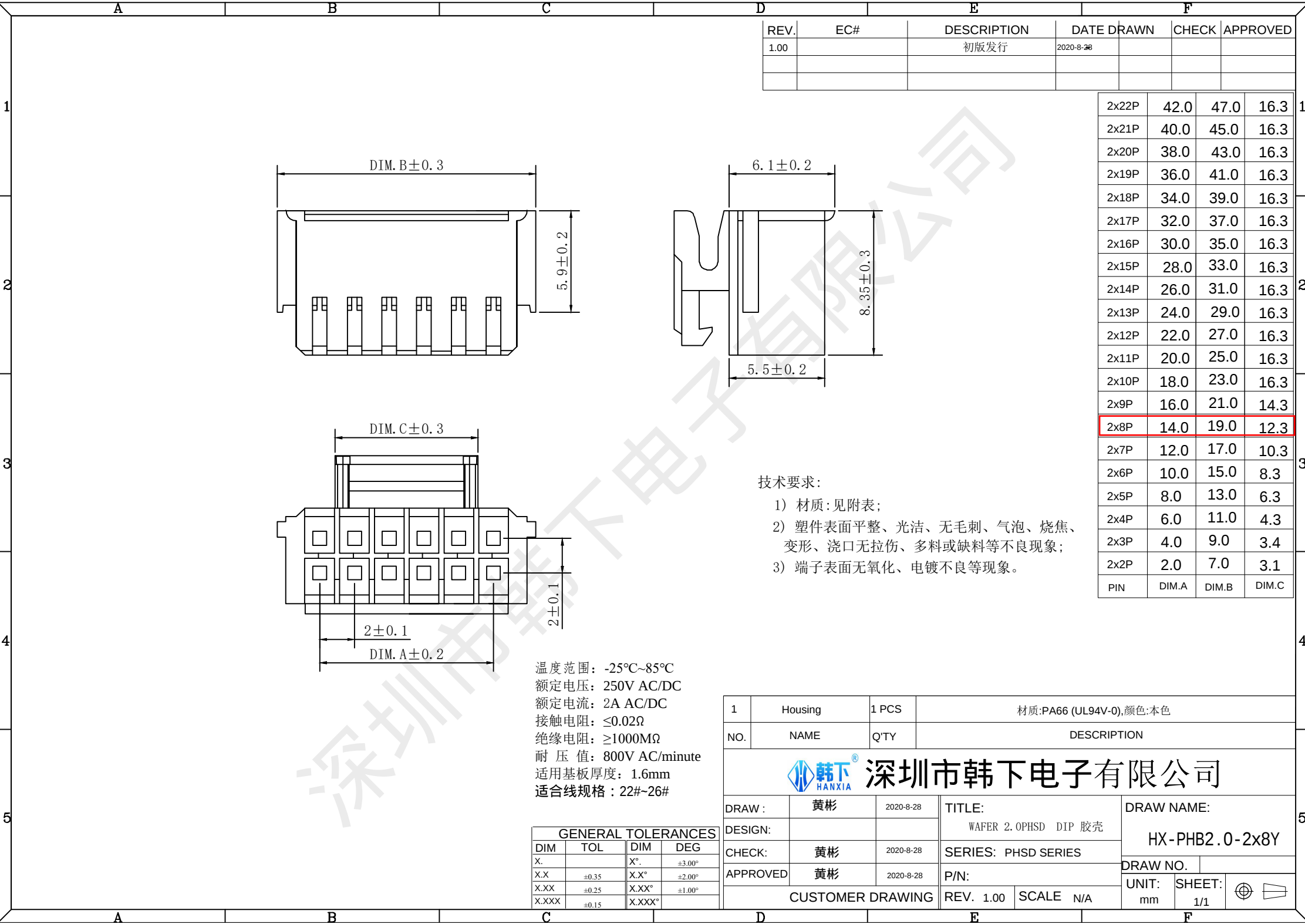




REV.	EC#	DESCRIPTION	DATE DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28		

2x22P	42.0	47.0	16.3
2x21P	40.0	45.0	16.3
2x20P	38.0	43.0	16.3
2x19P	36.0	41.0	16.3
2x18P	34.0	39.0	16.3
2x17P	32.0	37.0	16.3
2x16P	30.0	35.0	16.3
2x15P	28.0	33.0	16.3
2x14P	26.0	31.0	16.3
2x13P	24.0	29.0	16.3
2x12P	22.0	27.0	16.3
2x11P	20.0	25.0	16.3
2x10P	18.0	23.0	16.3
2x9P	16.0	21.0	14.3
2x8P	14.0	19.0	12.3
2x7P	12.0	17.0	10.3
2x6P	10.0	15.0	8.3
2x5P	8.0	13.0	6.3
2x4P	6.0	11.0	4.3
2x3P	4.0	9.0	3.4
2x2P	2.0	7.0	3.1
PIN	DIM.A	DIM.B	DIM.C

技术要求:

1) 材质: 见附表;

2) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;

3) 端子表面无氧化、电镀不良等现象。

温度范围: -25°C~85°C
额定电压: 250V AC/DC
额定电流: 2A AC/DC
接触电阻: ≤0.02Ω
绝缘电阻: ≥1000MΩ
耐 压 值: 800V AC/minute
适用基板厚度: 1.6mm
适合线规格: 22#~26#

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X.		X°	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	

1	Housing	1 PCS	材质:PA66 (UL94V-0),颜色:本色			
NO.	NAME	Q'TY	DESCRIPTION			
 韩下 深圳市韩下电子有限公司						
DRAW :	黄彬	2020-8-28	TITLE:		DRAW NAME:	
DESIGN:			WAFER 2.0PHSD DIP 胶壳		HX-PHB2.0-2x8Y	
CHECK:	黄彬	2020-8-28	SERIES: PHSD SERIES		DRAW NO.	
APPROVED	黄彬	2020-8-28	P/N:		UNIT:	SHEET:
CUSTOMER DRAWING			REV. 1.00	SCALE N/A	mm	1/1
						